

# 3D IC and 2.5D IC Market Report: Trends, Forecast and Competitive Analysis

<https://marketpublishers.com/r/32F2337A1FADEN.html>

Date: July 2024

Pages: 150

Price: US\$ 4,850.00 (Single User License)

ID: 32F2337A1FADEN

## Abstracts

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The future of the 3D IC and 2.5D IC market looks promising with opportunities in the consumer electronics, telecommunication, industrial, automotive, military and aerospace, smart technology, and medical device industries. The global 3D IC and 2.5D IC market is expected to decline in 2020 due to the global economic recession led by the COVID-19 pandemic. However, the market will witness recovery in the year 2021, and it is expected to grow with a CAGR of 37% to 39% from 2020 to 2025. The major drivers for this market are increasing demand for advanced architecture in electronics products and miniaturization of electronic devices.

A more than 150 page report is developed to help in your business decisions. Sample figures with some insights are shown below. To learn the scope of, benefits, companies researched and other details of 3D sensor market report download the report brochure.

The study includes trends and forecasts for the global 3D IC and 2.5D IC market by technology, application, end use industry, and region as follows:

By Technology [\$M shipment analysis for 2014 – 2025]:

3D Wafer-Level Chip-Scale Packaging

3D TSV

2.5D

By End Use Industry [\$M shipment analysis for 2014 – 2025]:

Consumer Electronics

Telecommunication

Industrial

Automotive

Military and Aerospace

Smart Technologies

Medical Devices

By Application [\$M shipment analysis for 2014 – 2025]

Logic

Imaging & Optoelectronics

Memory

MEMS/Sensors

LED

Power, Analog & Mixed Signal, RF, Photonics

By Region [\$M shipment analysis for 2014 – 2025]:

North America

United States

Canada

Mexico

Europe

Germany

United Kingdom

France

Italy

Asia Pacific

China

Japan

India

South Korea

The Rest of the World

Some of the 3D IC and 2.5D IC companies profiled in this report include Taiwan Semiconductor Manufacturing Company Ltd., Samsung Electronics, Toshiba Corp., Advanced Semiconductor Engineering Group, and Amkor Technology

Lucintel forecasts that logic will remain the largest application segment over the forecast period due to growing demand for 3D IC and 2.5D IC owing to high product availability.

Asia Pacific will remain the largest region during the forecast period due to growing demand for 3D IC and 2.5D IC in various consumer electronics products.

Features of 3D IC and 2.5D IC Market

Market Size Estimates: 3D IC and 2.5D IC market size estimation in terms of

value (\$M)

Trend and Forecast Analysis: Market trends (2014-2019) and forecast (2020-2025) by various segments and regions.

Segmentation Analysis: Market size by technology, application, and end use industry

Regional Analysis: 3D IC and 2.5D IC market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities: Analysis on growth opportunities in different technology, application, end use industry, and regions for 3D IC and 2.5D IC market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the 3D IC and 2.5D IC market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

This report answers following 11 key questions

Q.1 What are some of the most promising potential, high-growth opportunities for the global 3D IC and 2.5D IC market by technology (3D wafer-level chip-scale packaging, 3D TSV, and 2.5D), end use industry (consumer electronics, telecommunication, industrial, automotive, military and aerospace, smart technologies, medical devices), application (logic, imaging & optoelectronics, memory, MEMS/sensors, LED, and power, analog & mixed signal, RF, photonics), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q.2 Which segments will grow at a faster pace and why?

Q.3 Which regions will grow at a faster pace and why?

Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the 3D IC and 2.5D IC market?

Q.5 What are the business risks and threats to the 3D IC and 2.5D IC market?

Q.6 What are emerging trends in this 3D IC and 2.5D IC market and the reasons behind them?

Q.7 What are some changing demands of customers in the 3D IC and 2.5D IC market?

Q.8 What are the new developments in the 3D IC and 2.5D IC market? Which

companies are leading these developments?

Q.9 Who are the major players in the 3D IC and 2.5D IC market? What strategic initiatives are being implemented by key players for business growth?

Q.10 What are some of the competitive products and processes in the 3D IC and 2.5D IC market, and how big of a threat do they pose for loss of market share via material or product substitution?

Q.11 What M&A activities did take place in the last five years in the 3D IC and 2.5D IC market?

## Contents

### **1. EXECUTIVE SUMMARY**

### **2. MARKET BACKGROUND AND CLASSIFICATIONS**

2.1: Introduction, Background, and Classifications

2.2: Supply Chain

2.3: Industry Drivers and Challenges

### **3. MARKET TRENDS AND FORECAST ANALYSIS FROM 2014 T 2025**

3.1: Macroeconomic Trends (2014-2019) and Forecast (2020-2025)

3.2: Global 3D IC and 2.5D IC Market Trends (2014-2019) and Forecast (2020-2025)

3.3: Global 3D IC and 2.5D IC Market by End Use Industry

3.3.1: Consumer Electronics

3.3.2: Telecommunication

3.3.3: Industrial

3.3.4: Automotive

3.3.5: Military and Aerospace

3.3.6: Smart technologies

3.3.7: Medical devices

3.4: Global 3D IC and 2.5D IC Market by Technology

3.4.1: 3D wafer-level chip-scale packaging

3.4.2: 3D TSV

3.4.3: 2.5D

3.5: Global 3D IC and 2.5D IC Market by Application

3.5.1: Logic

3.5.2: Imaging & optoelectronics

3.5.3: Memory

3.5.4: MEMS/Sensors

3.5.5: LED

3.5.6: Power, analog & mixed signal, RF, photonics

### **4. MARKET TRENDS AND FORECAST ANALYSIS BY REGION FROM 2014 T 2025**

4.1: Global 3D IC and 2.5D IC Market by Region

4.2: North American 3D IC and 2.5D IC Market

4.2.1: Market by End Use Industry

- 4.2.2: Market by Technology
- 4.2.3: Market by Application
- 4.2.4: The US 3D IC and 2.5D IC Market
- 4.2.5: The Canadian 3D IC and 2.5D IC Market
- 4.2.6: The Mexican 3D IC and 2.5D IC Market
- 4.3: European 3D IC and 2.5D IC Market
  - 4.3.1: Market by End Use Industry
  - 4.3.2: Market by Technology
  - 4.3.3: Market by Application
  - 4.3.4: German 3D IC and 2.5D IC Market
  - 4.3.5: United Kingdom 3D IC and 2.5D IC Market
  - 4.3.6: French 3D IC and 2.5D IC Market
  - 4.3.7: Italian 3D IC and 2.5D IC Market
- 4.4: APAC 3D IC and 2.5D IC Market
  - 4.4.1: Market by End Use Industry
  - 4.4.2: Market by Technology
  - 4.4.3: Market by Application
  - 4.4.4: Chinese 3D IC and 2.5D IC Market
  - 4.4.5: Japanese 3D IC and 2.5D IC Market
  - 4.4.6: Indian 3D IC and 2.5D IC Market
  - 4.4.7: South Korean 3D IC and 2.5D IC Market
- 4.5: ROW 3D IC and 2.5D IC Market
  - 4.5.1: Market by End Use Industry
  - 4.5.2: Market by Technology
  - 4.5.3: Market by Application

## **5. COMPETITOR ANALYSIS**

- 5.1: Product Portfoli Analysis
- 5.2: Geographical Reach
- 5.3: Porter's Five Forces Analysis

## **6. GROWTH OPPORTUNITIES AND STRATEGIC ANALYSIS**

- 6.1: Growth Opportunity Analysis
  - 6.1.1: Growth Opportunities for the Global 3D IC and 2.5D IC Market by End Use Industry
  - 6.1.2: Growth Opportunities for the Global 3D IC and 2.5D IC Market by Technology
  - 6.1.3: Growth Opportunities for the Global 3D IC and 2.5D IC Market by Application

- 6.1.4: Growth Opportunities for the Global 3D IC and 2.5D IC Market by Region
- 6.2: Emerging Trends in the Global 3D IC and 2.5D IC Market
- 6.3: Strategic Analysis
  - 6.3.1: New Product Development
  - 6.3.2: Capacity Expansion of the Global 3D IC and 2.5D IC Market
  - 6.3.3: Technology Development
  - 6.3.4: Mergers and Acquisitions in the Global 3D IC and 2.5D IC Industry

## **7. COMPANY PROFILES OF LEADING PLAYERS**

- 7.1: Taiwan Semiconductor Manufacturing Company
- 7.2: Samsung Electronics
- 7.3: Toshiba Corp.
- 7.4: Advanced Semiconductor Engineering Group
- 7.5: Amkor Technology



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